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(54) Title: AQUEOUS ACIDIC FORMULATIONS FOR COPPER OXIDE ETCH RESIDUE REMOVAL AND PREVENTION
OF COPPER ELECTRODEPOSITION

(57) Abstract: A highly aqueous acidic cleaning composition for copper oxide etch removal from Cu-dual damascene microelec-
tronic structures and wherein that composition prevents or substantially eliminates copper redeposition on the Cu-dual damascene
microelectronic structure.



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